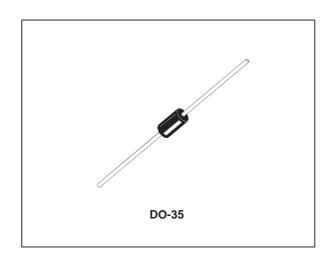


# SMALL SIGNAL SCHOTTKY DIODES



#### **DESCRIPTION**

General purpose, metal to silicon diodes featuring very low turn-on voltage fast switching.

These devices have integrated protection against excessive voltage such as electrostatic dis-

## **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit	
$V_{RRM}$	Repetitive Peak Reverse Voltage	30	V	
I <sub>F</sub>	Forward Continuous Current $T_a = 25$ °C		200	mA
I <sub>FRM</sub>	Repetitive Peak Fordware Current $ t_p \leq 1s \\ \delta \leq 0.5 $		500	mA
I <sub>FSM</sub>	Surge non Repetitive Forward Current* t <sub>p</sub> = 10ms		4	Α
$P_{tot}$	Power Dissipation*	200	mW	
$T_{stg} \\ T_{j}$	Storage and Junction Temperature Range		- 65 to +150 - 65 to +125	°C °C
TL	Maximum Temperature for Soldering during 1 Case	230	°C	

#### THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R <sub>th(j-a)</sub>	Junction-ambient*	300	°C/W

<sup>\*</sup> On infinite heatsink with 4mm lead length

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## **ELECTRICAL CHARACTERISTICS**

## STATIC CHARACTERISTICS

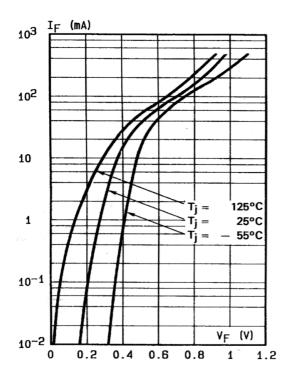
Symbol	Test Conditions			Min.	Тур.	Max.	Unit
$V_{BR}$	Tj = 25°C	$I_R = 100 \mu A$		30			V
V <sub>F</sub> *	T <sub>j</sub> = 25°C	$I_F = 200 \text{mA}$	All Types			1	V
	T <sub>j</sub> = 25°C	$I_F = 10 \text{mA}$	BAT 42			0.4	
	T <sub>j</sub> = 25°C	$I_F = 50 \text{mA}$				0.65	
	T <sub>j</sub> = 25°C	$I_F = 2mA$	BAT 43	0.26		0.33	
	T <sub>j</sub> = 25°C	$I_F = 15mA$				0.45	
I <sub>R</sub> *	T <sub>j</sub> = 25°C		V <sub>R</sub> = 25V			0.5	μА
	T <sub>j</sub> = 100°ÉC					100	

## **DYNAMIC CHARACTERISTICS**

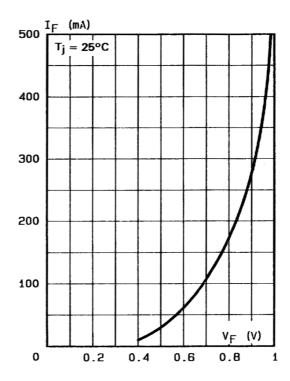
Symbol	Test Conditions		Тур.	Max.	Unit
С	$T_j = 25$ °C $V_R = 1$ V $f = 1$ MHz		7		pF
trr	$Tj = 25^{\circ}C$ $I_F = 10mA$ $I_R = 10mA$ $I_{rr} = 1mA$ $R_L = 100\Omega$			5	ns
h	$T_j = 25^{\circ}C$ $R_L = 15K\Omega$ $C_L = 300pF$ $f = 45MHz$ $V_i = 2V$	80			%

<sup>\*</sup> Pulse test:  $t_p \le 300 \mu s$   $\delta < 2\%$ .

**Fig. 1:** Forward current versus forward voltage at different temperatures (typical values).

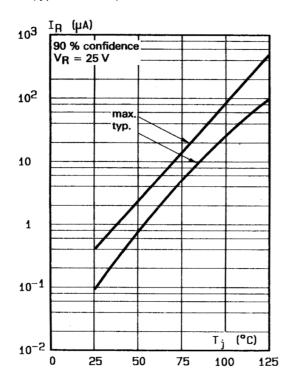


**Fig. 2:** Forward current versus forward voltage (typical values).



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**Fig. 3:** Reverse current versus junction temperature (typical values).



**Fig. 4:** Reverse current versus continuous reverse voltage.

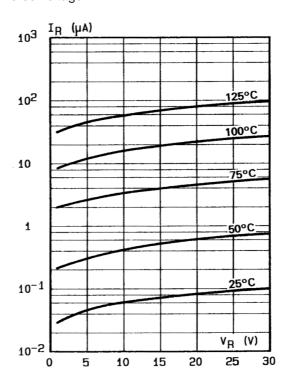
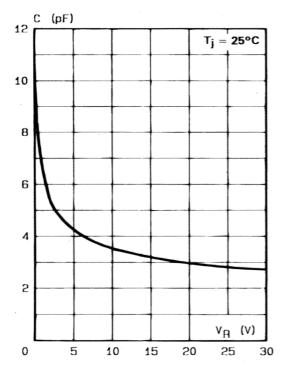


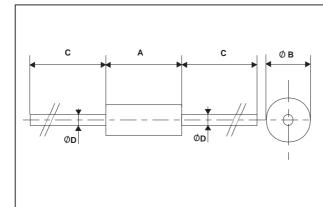
Fig. 5: Capacitance C versus reverse applied voltage  $V_{\scriptscriptstyle R}$  (typical values).



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#### **PACKAGE MECHANICAL DATA**

DO-35



REF.	DIMENSIONS			
	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
А	3.05	4.50	0.120	0.177
В	1.53	2.00	0.060	0.079
С	28.00		1.102	
D	0.458	0.558	0.018	0.022

Cooling method: by convection and conduction

Marking: clear, ring at cathode end.

Weight: 0.15g

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